

Title (en)

Wafer chamfering method and apparatus

Title (de)

Verfahren und Vorrichtung zum Abfasen von Halbleiterscheiben

Title (fr)

Procédé et dispositif pour chamfreiner une plaquette semiconductrice

Publication

EP 0962282 B1 20030903 (EN)

Application

EP 98304467 A 19980605

Priority

EP 98304467 A 19980605

Abstract (en)

[origin: EP0962282A1] A wafer (W) to be chamfered is supported in such a manner as to rotate and to move in the X-axis direction and the Y-axis direction which are perpendicular to one another, and a periphery grinding wheel (48) is rotatably placed on the Y-axis. To chamfer a circular part (C) of the wafer (W), the circular part (C) of the wafer (W) is pressed against the rotating periphery grinding wheel (48), and then, the wafer (W) is rotated. To chamfer an orientation flat (OF) of the wafer (W), the orientation flat (OF) of the wafer (W) is pressed against the rotating periphery grinding wheel (48), and then, the wafer (W) is fed in the X-axis direction. <IMAGE>

IPC 1-7

B24B 9/06; **B24B 47/10**; **B24B 51/00**

IPC 8 full level

B24B 9/06 (2006.01); **B24B 47/10** (2006.01); **B24B 51/00** (2006.01)

CPC (source: EP)

B24B 9/065 (2013.01); **B24B 47/10** (2013.01); **B24B 51/00** (2013.01)

Cited by

JP2019198899A; JP2017081782A

Designated contracting state (EPC)

DE GB IT

DOCDB simple family (publication)

EP 0962282 A1 19991208; **EP 0962282 B1 20030903**; DE 69817771 D1 20031009; DE 69817771 T2 20040311

DOCDB simple family (application)

EP 98304467 A 19980605; DE 69817771 T 19980605